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IL – ASCE 2008 Scholarship Notice

INTRODUCTION TO ENGINEERING PROGRAM UNIVERSITY OF NOTRE DAME

Session 1: June 15 - July 3, 2008

Session 2: July 6 - July 24, 2008

The Illinois Section of the American Society of Civil Engineers (IL-ASCE) is seeking applications from minority students interested in participating in a three-week summer Introduction to Engineering Program at the University of Notre Dame. The program is designed to provide high school students with a broad exposure to the profession of engineering and to motivate those who possess an interest in pursuing a career in this challenging field. During the three-week program at the University of Notre Dame campus (located near South Bend, Indiana), participants will attend lectures and participate in hands-on laboratory exercises related to the various fields of engineering analysis and design, computer programming, and other special topics. In addition, students will gain the experience of living in a university environment for a three-week period.

Applicants must be completing their Junior year in high school and have completed (by the end of the school year) three years of high school level mathematics and one year of science (either chemistry or physics) courses.

As part of its ongoing commitment to encouraging minority students to consider engineering as a career, the IL-ASCE will be providing a limited number of full scholarships (tuition, room and board, and transportation) for this program. In order to be considered for a scholarship, interested students should complete the following and send it to the address below: (1) the attached application form, (2) a letter explaining why they would like to participate in the program and (3) a letter of recommendation from a guidance counselor or teacher.

Carlos Nazario

Tel: (312) 371-2745

PMA Consultants of Illinois
333 West Wacker Dr.

E-mail: cnazario@pmaconsultants.com

Ste. 880

Chicago, IL 60606

The attached IL-ASCE Scholarship Application must be received by April 15, 2008.

Please contact Carlos Nazario at (312) 371-2745 with questions regarding the program or the scholarship applications.